

Barrier Selection Rules for Quantum Dots-in-a-Well Infrared Photodetector

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Abstract—We report on a systematic study of the effect of barriers on quantum dots-in-a-well infrared photodetectors. Four devices are fabricated and characterized with varying composition for barriers adjacent to quantum dots and away from quantum dots. Effects of these “proximity” and “remote” barriers are studied by comparing photoluminescence, responsivity, dark current, background-limited operating temperature, activation energy, and detectivity. The growth mechanism for a conformal coverage of quantum dots with proximity barriers is described and supported with reflection high-energy electron diffraction and transmission electron microscopy images. It is shown that proximity barriers and remote barriers influence the characteristics of the detector very differently, with increases in proximity barrier energy leading to higher responsivity and lower dark current, while remote barriers reduce the responsivity and dark currents simultaneously. It is demonstrated that confinement enhancing barriers as proximity barriers optimize the SNR at low bias range, suitable for focal plane array applications.

Index Terms—Barriers, confinement enhancing barriers quantum dots, quantum dots in a well (DWELL).

I. INTRODUCTION

QUANTUM dot infrared photodetectors (QDIP) [1]–[5], have been actively studied in the last few years due to

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their potential for high operating temperature imaging [6], drawing from the already established quantum well infrared photodetector (QWIP) technology. However, it is hard to control the peak detection wavelengths in QDIPs due to the sensitivity of growth of Stranski-Krastanov (SK) quantum dots on growth parameters [7]. Quantum dots-in-a-well (DWELL) architecture [8]–[14] in which, typically, InAs (or InGaAs) quantum dots are embedded in InGaAs-GaAs quantum well or InGaAs-GaAs-AlGaAs double quantum well [15], provides a viable alternative to traditional QDIP designs. DWELL architecture allows better material growth characteristics and the ability to precisely and predictably control the peak wavelengths just by changing the composition and dimensions of quantum wells. Characteristics of DWELL detectors, such as responsivity, spectral response, dark current, photoconductive gain etc are highly dependent, and hence tunable, on the details of barrier designs and growth characteristics. In this paper, important relationships between these characteristics to barrier design parameters will be discussed.

DWELL detectors with AlGaAs barriers provide several excited states in the conduction band, leading to a bias tunable multicolor operation [14], [16], [17]. For high operating temperatures, the most important requirement is low dark current, such that charge wells in readout integrated circuits (ROIC) are not saturated. In traditional DWELL designs, however, there is a tradeoff between the dark current level, the responsivity and the peak wavelength. For example, if the AlGaAs barrier energy increases, the dark current level drops exponentially, but the escape probability of the photoexcited, bound electrons also decreases, leading to a decrease in the responsivity. Since longwave infrared (LWIR) carriers are bound deep inside, they cannot escape at low bias levels, thus limiting the maximum detection wavelength. Other effect is increase in the optimal operating bias [2], [12], [16], [18], with the increase in AlGaAs barrier energy. Since typical ROIC bias levels are limited to low values, these designs are not well suited for FPA imaging.

It has been previously demonstrated [19] that bound to quasibound (B-Q) type of transitions, in which the infrared absorption takes place between a bound state in quantum dot and a quasibound state very close to the barrier conduction band energy, optimizes the detectivity at moderate bias, leading to high operating temperatures [20]. These transitions combine the advantages of bound to continuum (B-C) transitions, such as, high escape probability, low bias operation

with those of bound to bound (B-B) types of transitions, such as high absorption quantum efficiency. Performance of B-Q type of transitions can be further improved with confinement enhanced (CE) barriers [21]. CE DWELL detectors have been previously demonstrated [21] to increase the responsivity and decrease the noise, simultaneously, for a low bias operation, thus increasing the signal to noise ratio (SNR).

There are several design parameters in the design of DWELL devices for FPA applications, such as the absolute values of dark current and responsivity, the spectral range, detectivities and the optimum operating bias. In this work, we perform a series of systematic experiments in order to understand the tradeoff associated with different barrier configurations for optimizing these parameters. We compare the characteristics of CE DWELL detectors with different traditional barrier compositions and spacing to examine the device design rules for optimizing the signal to noise ratio at a lower bias. Four devices were designed and fabricated with different ‘proximity barriers’, which are barriers adjacent to the DWELL region and ‘remote barriers’ which are thick barriers separating the DWELL regions to avoid strain coupling and inter-dot tunneling. CE DWELL designs have been shown to optimize the SNR at lower bias amongst the four devices.

II. DEVICE DESIGNS

Fig. 1(a)–(d) shows the schematics of four devices (A, B, C and D) designed for this study. Only the locations of the ground state energy levels of quantum dots and confined state energy levels in quantum wells are shown. These energies are extracted with a semi-empirical approach, based on the photocurrent spectra, photoluminescence (PL) data and known conduction band offsets between the materials. In all the devices, InAs quantum dots with 2 monolayer (ML) nominal thickness are embedded in $\text{In}_{0.15}\text{Ga}_{0.85}\text{As}$ quantum well. Quantum dots are doped such that there are approximately 2 electrons per dot. Quantum wells and quantum dots are grown at 500 °C and barrier regions are grown at 590 °C. All the devices have 7 stacks of DWELL, each separated by 50 nm thick barrier regions and sandwiched between n-doped contact regions. In device A, B and D, the 50 nm thick barrier separating the DWELL regions, here onwards called ‘remote barrier’ is $\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$, while in device C this barrier is composed of $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$. In device A, B and D, $\text{In}_{0.15}\text{Ga}_{0.85}\text{As}$ quantum well thickness is 1 nm below the quantum dot (strain bed) and 4.3 nm above the quantum dot (strain cap). In device C, the strain cap thickness was lowered to 3.5 nm, keeping the strain bed at 1 nm, in order to increase the escape probability of the electrons due to increase in the excited state energy.

Growth temperature changes are facilitated by growing 1 nm GaAs layer after the growth of remote barrier at high temperature and growing 1 nm GaAs after the strain cap at 500 °C, to avoid Indium desorption from the quantum well. We define the term ‘proximity barrier’ as the 2 nm region grown directly after the growth of 1 nm GaAs layer after the quantum well. Thus, in Device A, the proximity barrier is GaAs, in Device B, the proximity barrier is composed of $\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$, while

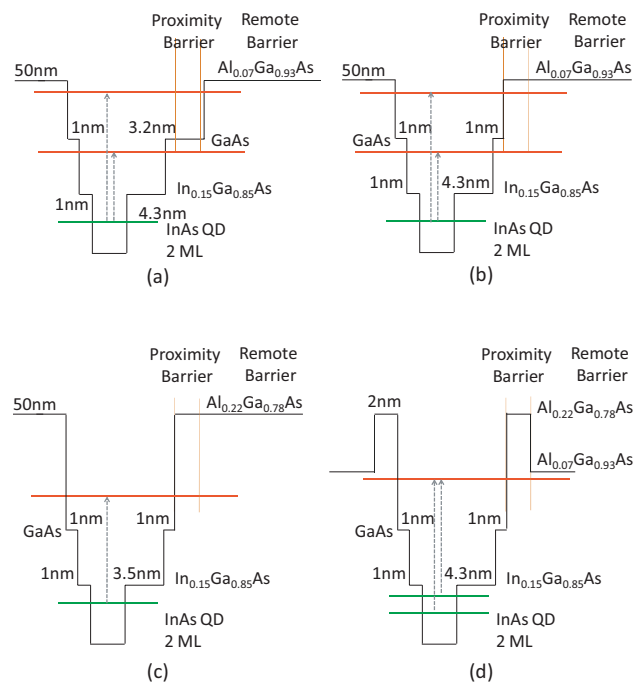


Fig. 1. Schematic conduction band diagram for (a) device A, (b) device B, (c) device C and (d) device D, showing the thicknesses, composition of various materials used, and approximate position of the ground-state and excited-state energies of interest. Primary transitions, corresponding to peaks in the spectral response are also marked. The diagrams are not to scale.

in Device C and D it is $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$. In device D, the proximity barrier serves as confinement enhancing barrier. Table I summarizes compositions of different barriers in all the devices. Temperature is ramped up after the growth of GaAs layer during a 3 minute long growth interruption. During this period, the excess InAs is evaporated off, leading to uniform height distribution and flat top quantum dots. This is important, as it assures that the barrier layers are grown on top of quantum dots. Therefore, it is clear that the InAs quantum dots are embedded within CE-barriers in device D, resulting in the effect of barrier in transverse direction. This can be justified by looking at reflection high energy electron diffraction (RHEED) pattern during the growth of the active region, as shown in Fig. 2.

Fig. 2(a) shows the chevron-type RHEED pattern, typical of SK quantum dots. Fig. 2(b) shows spotty RHEED pattern during the InGaAs capping, indicating that the quantum dots are not yet fully covered, which changes to a streak pattern during the GaAs capping layer growth. After this capping layer, during the temperature ramping, the pattern shows sharp lines, thus indicating that the excess Indium has been evaporated from larger quantum dots which are not fully covered by the capping layer. This insures that the CE-barriers are grown over the quantum dots.

The conformal coverage of the CE barriers over the quantum dots was also confirmed with transmission electron microscopy (TEM). Fig. 3 shows some of the images obtained with sample D. Fig. 3(a) shows all the seven stacks with quantum dots. Excellent material quality with no visible defect can be observed. The quantum dot density is almost constant in all

TABLE I
SUMMARY OF COMPOSITIONS OF BARRIERS AND MEASURED ELECTRICAL PROPERTIES OF ALL THE STRUCTURES

Device	Proximity barrier	Remote barrier	Wavelength range (μm)	Optimal bias (V)	Responsivity at -0.4 V (77 K) (mA/W)	Dark current at -0.4 V (77 K) (A/cm^2)	Peak detectivity (77 K) ($\text{cm}\cdot\text{Hz}^{1/2}\cdot\text{W}^{-1}$)
A	GaAs	$\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$	4–11	± 0.2 – 0.8	10	3.9×10^{-5}	2.7×10^9
B	$\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$	$\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$	5–11	± 0.3 – 1	40	1.6×10^{-4}	6.8×10^9
C	$\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$	$\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$	5–8	± 2.5 – 3.5	0.3	$< 10^{-11}$ (system limited)	1.4×10^{11}
D	$\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$	$\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$	5–9	± 0.4 – 1.2	77	3.2×10^{-5}	7.3×10^{10}

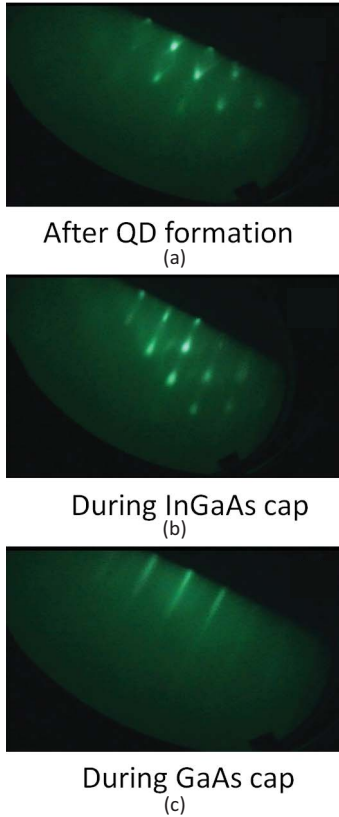


Fig. 2. RHEED patterns during the growth of different layers. (a) Chevron pattern after the quantum dot growth. (b) Spotty pattern during the capping layer growth, indicating partially capped quantum dots. (c) Streak pattern during the GaAs capping layer growth, indicating that the quantum dots are completely covered and the surface is flat.

the seven layers. Fig. 3(b) shows the expanded view of one of the quantum dots. A flat-top pyramidal quantum dots, with the base width of 16–18 nm and the height of 7 nm, along with a compressively strained $\text{In}_{0.15}\text{Ga}_{0.85}\text{As}$ quantum well is clearly visible. CE-barriers can be seen above and below the quantum well as bright stripes, although the contrast between $\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$ and $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ layers in this strain field map is low. Strain fields from the quantum dots above and below the quantum dots are visible.

III. RESULTS

After the MBE growth, photoluminescence measurement was done on with He-Ne laser at room temperature. Fig. 4

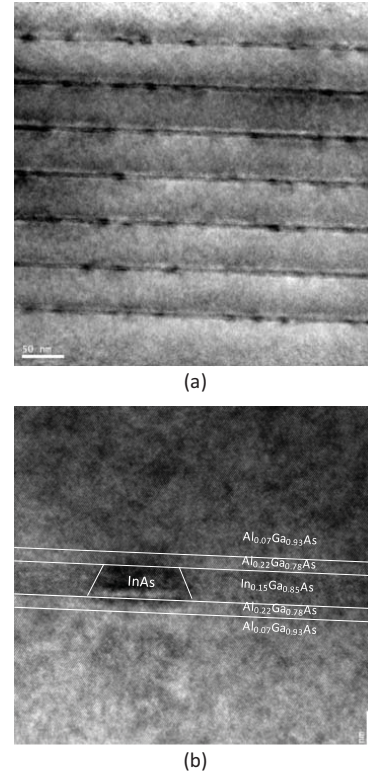


Fig. 3. TEM images of device D. (a) All seven stacks showing excellent material quality and dot uniformity. (b) Flat-top pyramidal quantum dot in a compressively strained InGaAs quantum well.

shows the normalized PL from all four devices. The peak of PL was found at 1154 nm (Device A), 1142 nm (Device B), 1076 nm (Device C) and 1118 nm (Device D). Clearly, as the Al concentration in the proximity barrier increase, e.g. GaAs for device A, $\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$ for device B and $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ in device C and D, the PL wavelength is blue-shifted. This is not only because of the increase in confinement due to barrier action, but could also be because Aluminum acts as a mechanical diffusion barrier, reducing the loss of confinement due to In to Ga interdiffusion, resulting in smaller quantum dots. Between device C and D, device C has lower PL peak wavelength due to a smaller strain cap thickness, resulting in smaller quantum dots. Interestingly, the PL intensity follows the same trend as PL wavelength, as it highest for device A and lowest for device C. This is due to interfacial defects caused by the

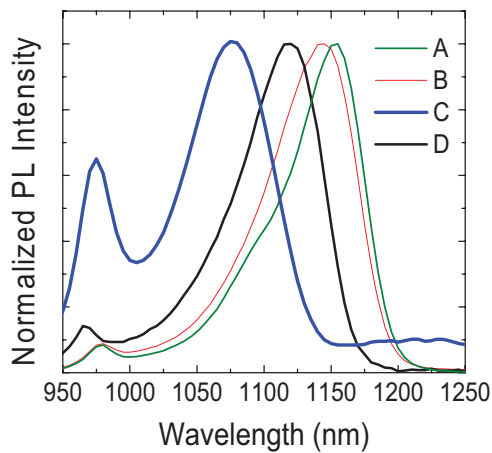


Fig. 4. Normalized PL spectra of all four devices measured using He-Ne laser at room temperature. Reduction in the peak wavelength is attributed to lowering of interdiffusion due to mechanical barrier action of Al. Device C has lower PL peak wavelength due to lower strain cap thickness above the quantum dot.

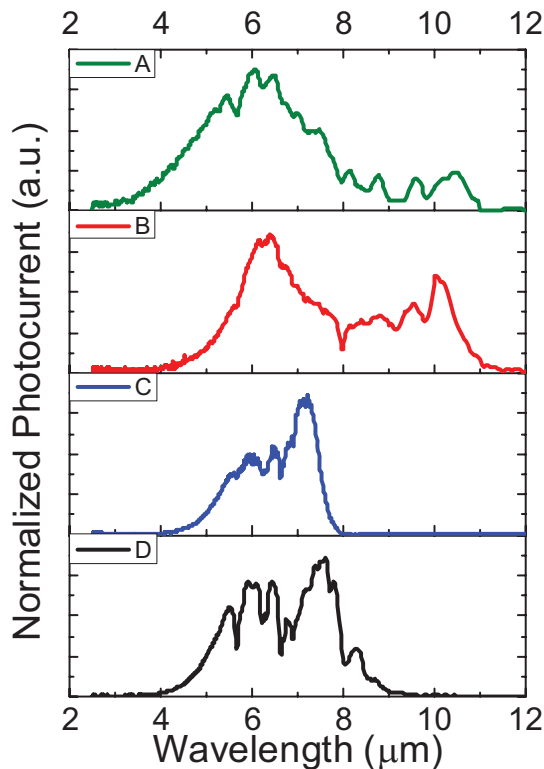


Fig. 5. Spectral response from the four devices at 77 K. The 10- to 10.5- μm peak present in devices A and B is absent in devices C and D due to the presence of Al_{0.22}Ga_{0.78}As barrier, which blocks long-wavelength carriers.

presence of Aluminum, and is believed to be growth system dependent.

The material was processed into $410 \times 410 \mu\text{m}^2$ single pixel devices for top-side illumination. The mesa patterns were etched with inductively coupled plasma etching, followed by a wet chemical etching. Ge/Au/Ni/Au contact metal was deposited and annealed to form ohmic contacts. These detectors were characterized in identical conditions for comparison. Fig. 5 shows the photocurrent spectrum comparison

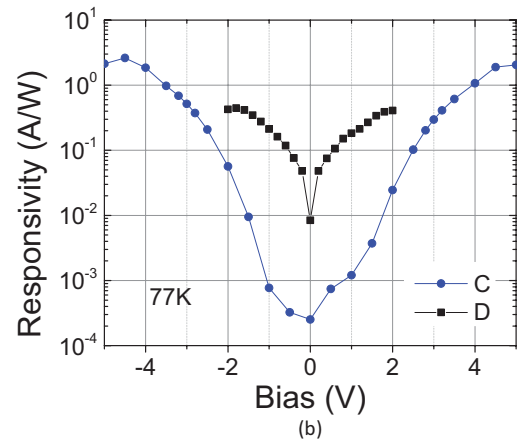
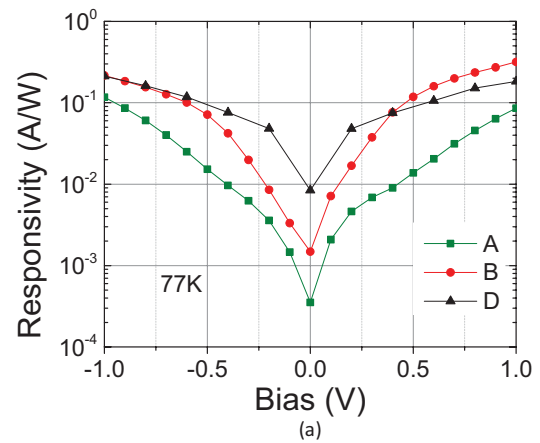


Fig. 6. (a) Effect of proximity barrier on the responsivity. Devices A, B, and D have same remote barrier. It is clear that as the proximity barrier energy increases, the responsivity increases due to better confinement in the excited state leading to a higher wavefunction overlap with the ground state. (b) Effect of remote barrier on the responsivity is much more drastic, with several orders of magnitude reduction in the responsivity due to the blocking of both photocarriers and dark current carriers by a large barrier.

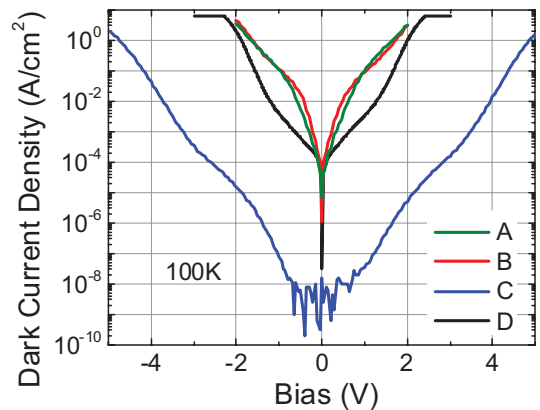


Fig. 7. Dark current density comparison between all devices at 100 K, showing several orders of magnitude reduction in the dark current for device C due to tall remote barrier. Device D also has more than an order of magnitude lower dark current as compared to devices A and B, due to the action of CE barriers.

between all four devices. As it can be seen from the schematics in Fig. 1(b) and 1(c), with the increase in the barrier energy, the excited level in the quantum well becomes more tightly confined. Due to enhanced confinement, the energy

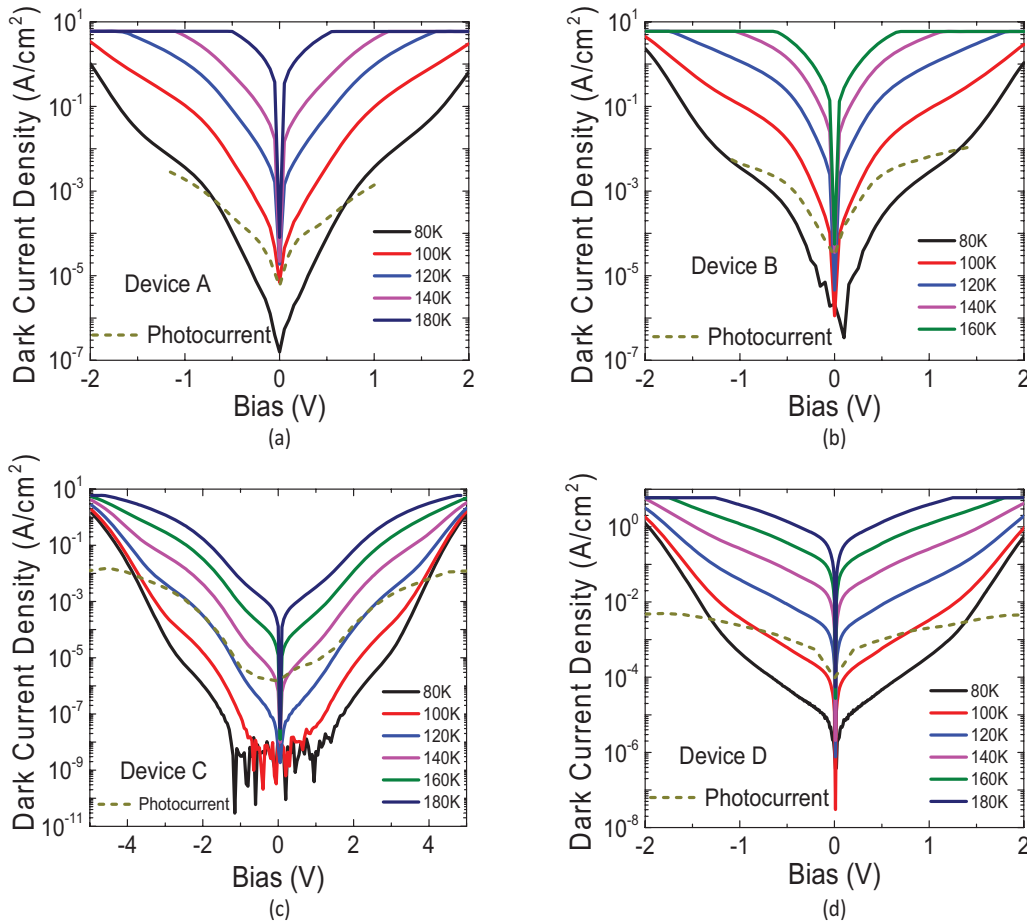


Fig. 8. Dark current density and photocurrent comparison (a) device A, (b) device B, (c) device C and (d) device D, to estimate the background limited infrared photodetection (BLIP) temperature.

separation between the two states also increases, which results in blue-shifting of the spectral response in device C. Due to larger energy step, long wavelength photoexcited electrons have poor escape probability. This results in blocking of long-wave carriers, as well as the requirement for high operating bias. This explains the spectral differences between device B and C. In device A, due to weaker confinement in the excited state, the broad midwave response, which results from bound to continuum type of transitions dominates over the longwave response. LWIR response at $10.5 \mu\text{m}$ is observable in device A and B, but with addition of $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ in the proximity barrier that peak is absent from device C and D. In device D, the peak at $7.55 \mu\text{m}$ comes from the transition between the first excited state in the quantum dot to the excited state in the quantum well, as suggested from the temperature dependent photocurrent spectra measurements.

Radiometric measurements were performed in liquid nitrogen cooled dewar with a calibrated blackbody setup. Fig 6(a) and (b) shows the responsivity for different proximity barriers (device A, B and D) and different remote barriers (device B and D), respectively, measured at 77K. Comparison between the responsivity of device A and B reveals that the responsivity of device A is lower than device B by close to an order of magnitude. For example, at a bias of 0.5V, the responsivity of device A is 13mA/W while that of device B is 110 mA/W. This increase in the responsivity, for a same

remote barrier and a similar spectral range is attributed to the increase in confinement due to higher energy proximity barrier. This trend continues, at lower biases, between device B and D, as highlighted in Table I. Due to confinement enhancing action of $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ CE-barriers, the responsivity is higher than device B, in the lower bias range. At higher bias, however, the device D starts saturating before device B, due to closeness of excited level in device D with respect to the remote barrier, as shown in Fig. 1. Fig. 5(b) reveals the effect of remote barrier on the responsivity. Device C has lowest responsivity at a given bias, but the bias range is much higher than other devices. The bias range in these measurements was limited by saturation of the preamplifier used to collect the current output. The lower responsivity, by a few orders of magnitude, in device C is a result of large energetic barrier provided by thick $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ remote barrier. This barrier blocks photocurrent carriers as well as dark current carriers, resulting in low responsivity as well as low dark current, as discussed later. These comparisons clearly indicate that the increase in the energy of the proximity barrier increases the responsivity, before it starts saturating at higher biases, while increase in the remote barrier drastically reduces the responsivity, and increases the operating bias range.

Fig. 7 compares the dark current densities obtained from all the four devices at 100K. As can be clearly seen, device C has more than five orders of magnitude lower dark current than

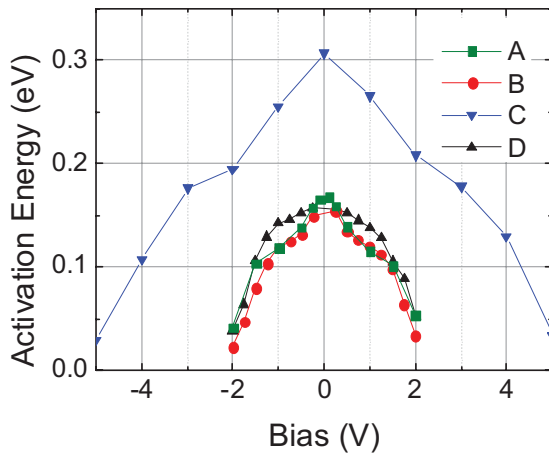


Fig. 9. Activation energy for the four devices confirming the proximity barrier's small effect and the remote barrier's large effect on the activation energy.

device D, which has a same proximity barrier but different remote barrier. This reduction is more than the reduction in the responsivity, as seen before, thus the overall signal to noise ratio is maintained high. Comparison between dark current density of device A and B reveals that the effect of increase in the barrier height for the proximity barrier on the dark current levels is negligible. However, device D has more than an order of magnitude lower dark current as compared to device A and B, as the proximity barrier is at higher energy than the remote barrier, which blocks some of the dark current carriers. Thus, the effect of CE barrier is to increase the responsivity while simultaneously lowering the dark current, thus increasing the overall signal to noise ratio.

Comparison of the dark current densities and photocurrent densities for all the samples at different temperatures is shown in Fig. 8(a)-(d). The photocurrent density was calculated by multiplying incident number of photons per second on the detector with the conversion efficiency of the detector, calculated from the measured responsivity. Responsivity value at 77K was used, as the change in responsivity with the increase in temperature is small. Comparison reveals that the background limited infrared photodetection (BLIP) condition is satisfied below 80K for device A and device B, 100K for device C and device D, at the optimum operating bias. The activation energies calculated from this data is plotted in Fig. 9. It shows that the activation energy is only weakly dependent on the composition of the proximity barrier, while is a strong function of the remote barrier energy. By changing the remote barrier to $\text{Al}_{0.22}\text{Ga}_{0.78}\text{As}$ from $\text{Al}_{0.07}\text{Ga}_{0.93}\text{As}$, the activation energy is increased by approximately 150 meV (bias dependent), which corresponds to increase in the barrier height. This is to be expected as the activation energy is approximately the difference between the barrier energy and the Fermi energy.

The most important figure of merit from the detector operation point of view is specific detectivity, which is the normalized signal to noise ratio. Fig. 10 compares the detectivity of all the four devices at 77K for $f/2$ optics. It is to be noted that the detectivity is underestimated at low bias

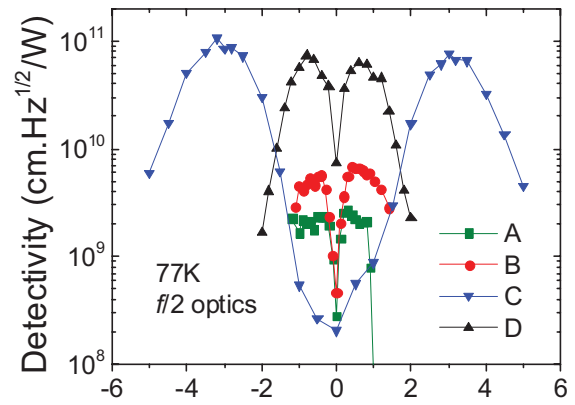


Fig. 10. Comparison of detectivities of all four devices at 77 K. This clearly shows that the increase in the proximity barrier energy increases the detectivity due to increase in signal and decrease in noise. This does not add to the operating bias for maximum detectivity. Device C, due to the presence of the large remote barrier, has high detectivity due to low dark current, but it needs large bias voltage for optimum performance.

in device C (from -2V to 2V) and D (from -0.4V to 4V) due to the system noise limit on the noise measurement. As expected, the detectivity increases from device A to device B, due to increase in responsivity. Device C has much higher detectivity as compared to device B, an order of magnitude increase. However, the peak detectivity is at -3V , which is too large bias for the FPA operation, due to limitations of typical ROICs. Device D, however, combines the best of both the worlds, with high detectivity at a low bias. It is to be noted that device D has a longer peak wavelength than device C.

IV. CONCLUSION

In conclusion, effects of proximity barrier and remote barrier on the device performance are very different in nature. As the proximity barrier energy increases, the confinement in the excited state of DWELL region increases, which leads to an increase in the wavefunction overlap with the ground state, thus increasing the responsivity, before it starts saturating at higher bias for large proximity barrier. The growth mechanism assures that the confinement enhancing barriers have been grown conformally over the quantum dot regions, as confirmed by RHEED and TEM images. Proximity barrier higher than the remote barrier, such as in device D, also leads to a dramatic reduction in dark current. The activation energy only weakly depends on the proximity barrier. On the contrary, as the remote barrier energy increases, both signal and dark currents are drastically reduced, the peak wavelength is blueshifted, and the activation energy is proportionally increased. This leads to high detectivities, but the optimum operating bias is also increased. Thus, with high detectivity, high responsivity, lower dark current, excellent optical quality of quantum dots and operation at low bias voltage suitable for focal plane array applications, device D, with CE-DWELL configuration optimizes the performance as it combines the advantages of large proximity barrier and small remote barrier.

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